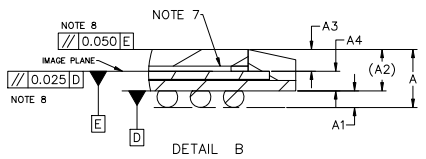
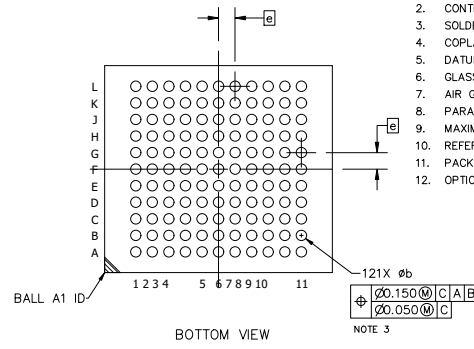
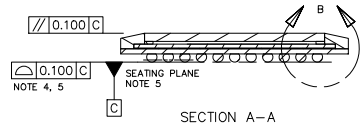
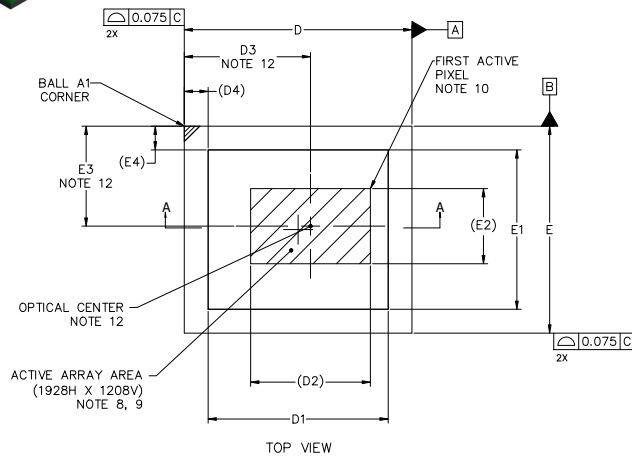


IBGA121 11.00x10.00x1.00, 0.80P
CASE 503BG
ISSUE C

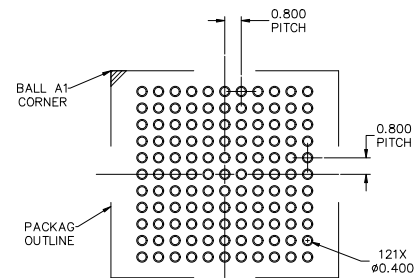
DATE 18 APR 2025



MILLIMETERS			
DIM	MIN	NOM	MAX
A	---	---	1.550
A1	0.350	0.400	0.4500
A2	1.000 REF		
A3	0.475	0.525	0.575
A4	0.425	0.475	0.525
b	0.450	0.500	0.550
D	10.925	11.000	11.075
D1	8.600	8.700	8.800
D2	5.784 REF		
D3	6.025	6.100	6.175
D4	1.150 REF		
E	9.925	10.000	10.075
E1	7.600	7.700	7.800
E2	3.624 REF		
E3	4.760	4.835	4.910
E4	1.150 REF		
e	0.800 BSC		

NOTES:

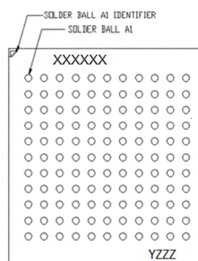
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2018.
2. CONTROLLING DIMENSION: MILLIMETERS [mm].
3. SOLDER BALL DIAMETER IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.
4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DATUM C, THE SEATING PLANE IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. GLASS: 0.400 THICKNESS; REFRACTIVE INDEX = 1.52; AR COATING R<0.5% 420-700nm (EACH SIDE).
7. AIR GAP BETWEEN GLASS AND PIXEL ARRAY: 0.125 THICKNESS.
8. PARALLELISM APPLIES ONLY TO THE ACTIVE ARRAY.
9. MAXIMUM ROTATION OF ACTIVE ARRAY RELATIVE TO DATUMS A AND B IS ±0.5°.
10. REFER TO THE DEVICE DATA SHEET FOR TOTAL PIXEL ARRAY DEFINITIONS.
11. PACKAGE CENTER (X, Y) = (0.000, 0.000).
12. OPTICAL CENTER RELATIVE TO PACKAGE CENTER (X, Y) = (0.600, 0.165).



RECOMMENDED MOUNTING FOOTPRINT*

*For additional information on our Pb-Free Strategy and Soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



XXXX = Specific Device Code
Y = Year
ZZZ = Lot Traceability

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	IBGA121 11.00x10.00x1.00, 0.80P	PAGE 1 OF 1

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